WNB160V5SPTS

Ultrafast power diode - Bare die

3 April 2018 Product data sheet

1. General description

Ultrafast power diode bare die.

2. Features and benefits

- Fast switching
- Low forward voltage drop
- Soft recovery characteristic
- Bare die

3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{RRM}*	repetitive peak reverse voltage			-	-	600	V
$I_{F(AV)}$**	average forward current	δ = 0.5 ; square-wave pulse		-	-	30	A
Static characteristics							
V_F**	forward voltage	I_F = 5 A; T_j = 25 °C		0.8	1.15	1.28	V
		I_F = 30 A; T_j = 25 °C		-	1.2	1.3	V
Dynamic characteristics							
t_{rr}**	reverse recovery time	I_F = 1A; dI_F/dt = 50 A/µs; V_R = 30 V; T_j = 25 °C;		-	-	75	ns

4. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
WNB160V5SPTS	Wafer	Bare die on wafer	Die

5. Limiting values

Table 2. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{RRM}*	repetitive peak reverse voltage			-	600	V
V_{RWM}*	crest working reverse voltage			-	600	V
V_R*	reverse voltage	DC		-	600	V
$I_{F(AV)}$**	average forward current	δ = 0.5 ; square-wave pulse		-	30	A
I_{FRM}**	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; square-wave pulse		-	60	A
I_{FSM}**	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		-	320	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; square-wave pulse		-	350	A
T_{stg}**	storage temperature			-55	175	°C
T_j**	junction temperature			-	175	°C

6. Characteristics

Table 3. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V_F**	forward voltage	I_F = 5 A; T_j = 25 °C		0.8	1.15	1.28	V
		I_F = 30 A; T_j = 25 °C		-	1.2	1.3	V
I_R	reverse current	V_R = 600 V; T_j = 25 °C		-	-	10	μA
		V_R = 600 V; T_j = 125 °C		-	-	500	μA
Dynamic characteristics							
t_{rr}**	reverse recovery time	I_F = 1A; dI_F/dt = 50 A/μs; V_R = 30 V; T_j = 25 °C;		-	-	75	ns

Notes:

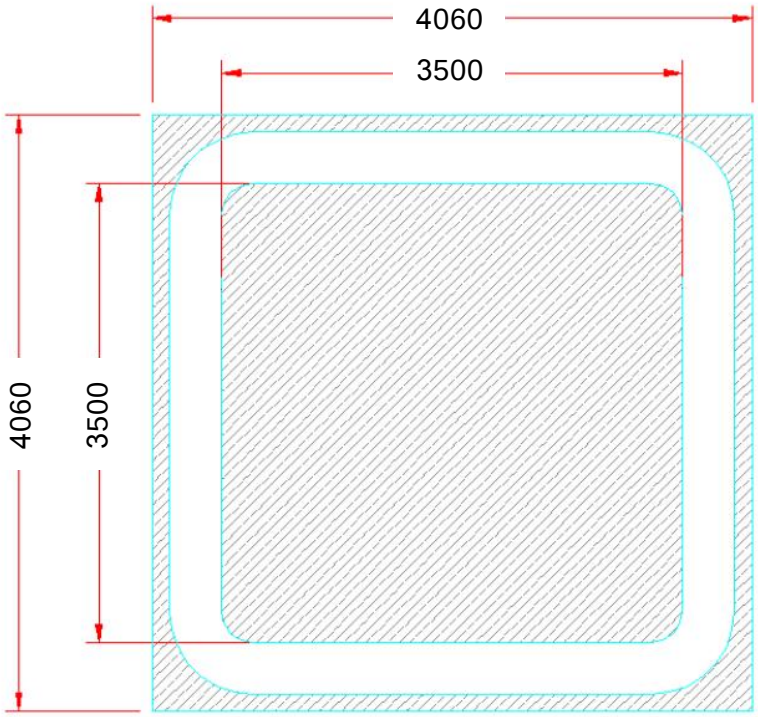
(1) * mean that parameter are 100% test at T_{amb} = 25°C.

(2) ** means that the guaranteed ratings and parameter limits will depend on the assembled structure. When correctly assembled with suitable die bonding and wire bonding, the device will have ratings and characteristics guaranteed in this data sheet.

MECHANICAL PARAMETER

Chip size	4.06 x 4.06	mm^2
Anode pad size	3.5 x 3.5	mm^2
Area total /active	16.48 /12.25	mm^2
Thickness	300	µm
Wafer size	125	mm
Max possible chips per wafer	658	pcs
Passivation	Glass	
Front metal	Al Ti Ni Ag	
Back metal	Ti Ni Ag	

CHIP LAYOUT



Die size: 4060um x 4060um
Bond pad size: 3500um x 3500um

7. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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7. Contents

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